

Title (en)

Cu-Ni-Si-Co COPPER ALLOY FOR ELECTRONIC MATERIAL AND PROCESS FOR PRODUCING SAME

Title (de)

CU-NI-SI-CO KUPFERLEGIERUNG FÜR EIN ELEKTRONISCHES MATERIAL UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

CU-NI-SI-CO ALLIAGE DE CUIVRE POUR MATÉRIEL ÉLECTRONIQUE ET SON PROCÉDÉ DE PRODUCTION

Publication

EP 2484787 B1 20150107 (EN)

Application

EP 09849834 A 20090928

Priority

JP 2009066794 W 20090928

Abstract (en)

[origin: EP2484787A1] A Cu-Ni-Si-Co alloy which has mechanical and electrical properties that render the alloy suitable for use as a copper alloy for electronic materials and which has even mechanical properties. The copper alloy for electronic materials contains 1.0-2.5 mass% nickel, 0.5-2.5 mass% cobalt, and 0.3-1.2 mass% silicon, with the remainder being copper and incidental impurities, and has an average crystal-grain diameter of 15-30 [μ]m, the average of differences between maximum crystal-grain diameter and minimum crystal-grain diameter for respective fields of view each having an area of 0.5 mm² being 10 [μ]m or smaller.

IPC 8 full level

C22C 9/06 (2006.01); **C22F 1/00** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP KR)

C22C 9/00 (2013.01 - KR); **C22C 9/06** (2013.01 - EP KR); **C22F 1/08** (2013.01 - EP KR)

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